



## Material Content Data Sheet



<b>Sales Product Name</b>		ICE2HS01G		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA003078274						
<b>Package</b>		PG-DSO-20-45		<b>Weight*</b>		587.30 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.580	0.44	0.44	4392	4392
leadframe	inorganic material	phosphorus	7723-14-0	0.047	0.01		81	
	non noble metal	zinc	7440-66-6	0.190	0.03		323	
	non noble metal	iron	7439-89-6	3.797	0.65		6466	
wire	non noble metal	copper	7440-50-8	154.185	26.25	26.94	262534	269404
	noble metal	gold	7440-57-5	0.576	0.10	0.10	980	980
	encapsulation	organic material	carbon black	1333-86-4	0.838	0.14		1427
encapsulation	plastics	epoxy resin	-	38.563	6.57		65661	
	inorganic material	silicondioxide	60676-86-0	379.758	64.66	71.37	646621	713709
leadfinish	non noble metal	tin	7440-31-5	4.487	0.76	0.76	7640	7640
plating	noble metal	silver	7440-22-4	0.800	0.14	0.14	1362	1362
glue	plastics	epoxy resin	-	0.369	0.06		628	
	noble metal	silver	7440-22-4	1.107	0.19	0.25	1885	2513
*deviation	< 10%				Sum in total:		100.00	1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com